



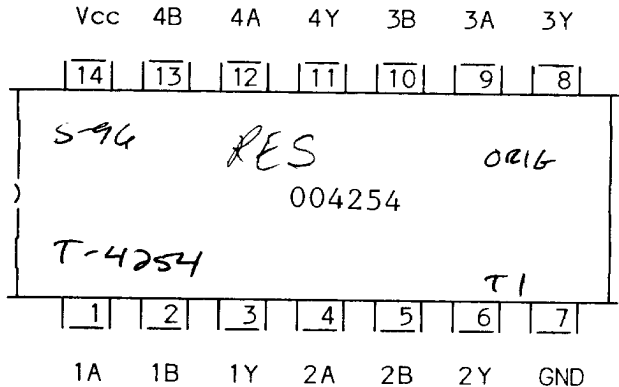
ADVANCED LOW-POWER  
SCHOTTKY TTL

TYPES SN54ALS900 and SN74ALS900  
QUAD 2-INPUT NAND BUFFERS

- \* QUAD 2- INPUT NAND BUFFERS
- \* ADVANCED OXIDE-ISOLATED, ION-IMPLANTED SCHOTTKY TTL PROCESS
- \* FUNCTIONALLY and PIN-for-PIN COMPATIBLE with TTL COUNTERPART
- \* IMPROVED AC PERFORMANCE over LS COUNTERPART
- \* HALF the POWER of LS COUNTERPART
- \* IMPROVED INPUT THRESHOLD VOLTAGE
- \* IMPROVED LINE RECEIVING CHARACTERISTICS

ELECTRICAL PINOUT

positive logic:  $Y = \overline{AB}$



This advanced low-power Schottky device has been fabricated by an advanced oxide-isolated, ion-implanted Schottky TTL process developed by TI. The major benefit of this process is the improvement of the speed-power product by the reduction of parasitic and side-wall capacitance and enhanced  $f_T$ . The ALS family features the same output drive characteristics as the LS family.

switching characteristics  $V_{CC}=5V, T_a=25^\circ C, C_l=50pF, R_l=667ohms$

PARAMETER		SN54ALS900		SN74ALS900		UNIT
		min	typ max	min	typ max	
t <sub>plh</sub>	Propagation delay time, low-to-high-level output	3.5		3.5		ns
t <sub>phl</sub>	Propagation delay time, high-to-low-level output	3.5		3.5		ns

supply current over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS	SN54ALS900		SN74ALS900		UNIT
		typ	max	typ	max	
I <sub>ccH</sub>	Supply current, outputs high	.86	2.1	.86	2.1	mA
I <sub>ccL</sub>	Supply current, outputs low	4.0	6.8	4.0	6.8	mA

PARAMETER	TEST CONDITIONS	SN54ALS900		SN74ALS900		UNIT
		min	max	min	max	
I <sub>o†</sub>	Output drive current	-15 -70		-15 -70		mA

† The output voltage conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I<sub>os</sub>.